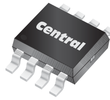
Material Composition Specification

SOIC-8 Case



Device average mass . . . . 74.6 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.43%	0.32	Si	7440-21-3	0.43%	0.32	4,290
bond wire	copper	0.03%	0.02	Cu	7440-50-8	0.03%	0.02	268
leadframe	Cu alloy w/ silver plating	38.87%	29	Cu	7440-50-8	37.47%	27.95	374,665
				Fe	7439-89-6	0.912%	0.68	9,115
				P	7723-14-0	0.027%	0.02	268
				Zn	7440-66-6	0.04%	0.03	402
				Ag	7440-22-4	0.429%	0.32	4,290
die attach	silver epoxy	0.094%	0.07	Ag	7440-22-4	0.075%	0.056	751
				epoxy resin	Proprietary	0.019%	0.014	188
encapsulation*	EMC GREEN	60.56%	45.2	silica (fused)	60676-86-0	42.9%	32	428,954
				epoxy resin	29690-82-2	5.63%	4.2	56,300
				phenol resin	9003-35-4	5.63%	4.2	56,300
				carbon black	1333-86-4	0.31%	0.23	3,083
				metal hydroxide	1309-42-8	6.1%	4.55	60,992
plating	matte tin	0.013%	0.01	Sn	7440-31-5	0.013%	0.01	134

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.